



SUSS MICROTEC INVESTOR PRESENTATION

November 2014

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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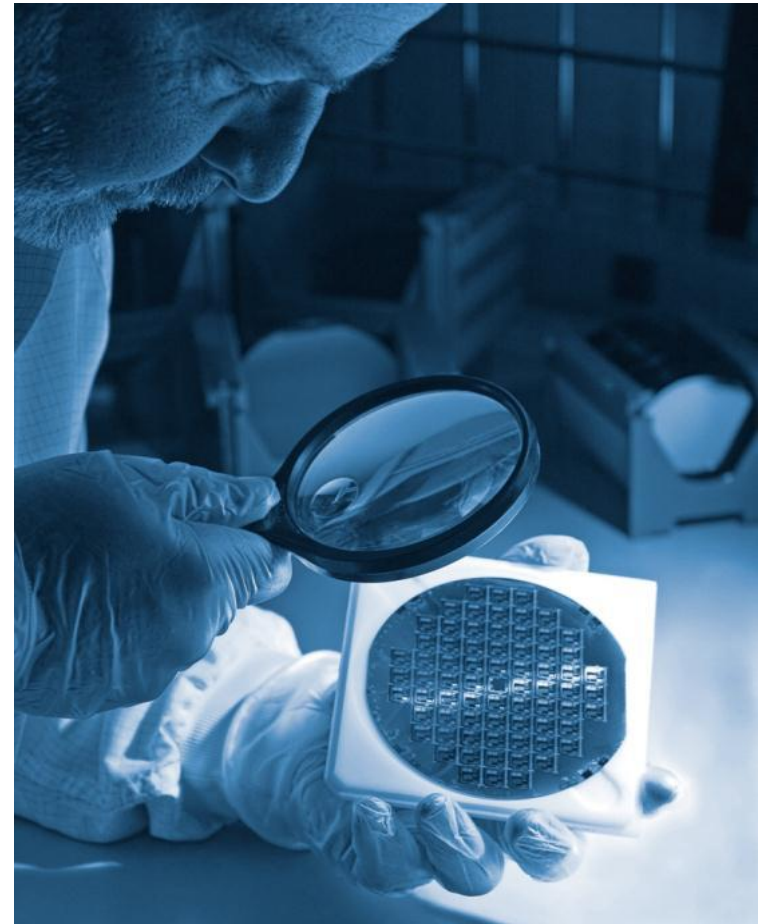
II. Products and Markets

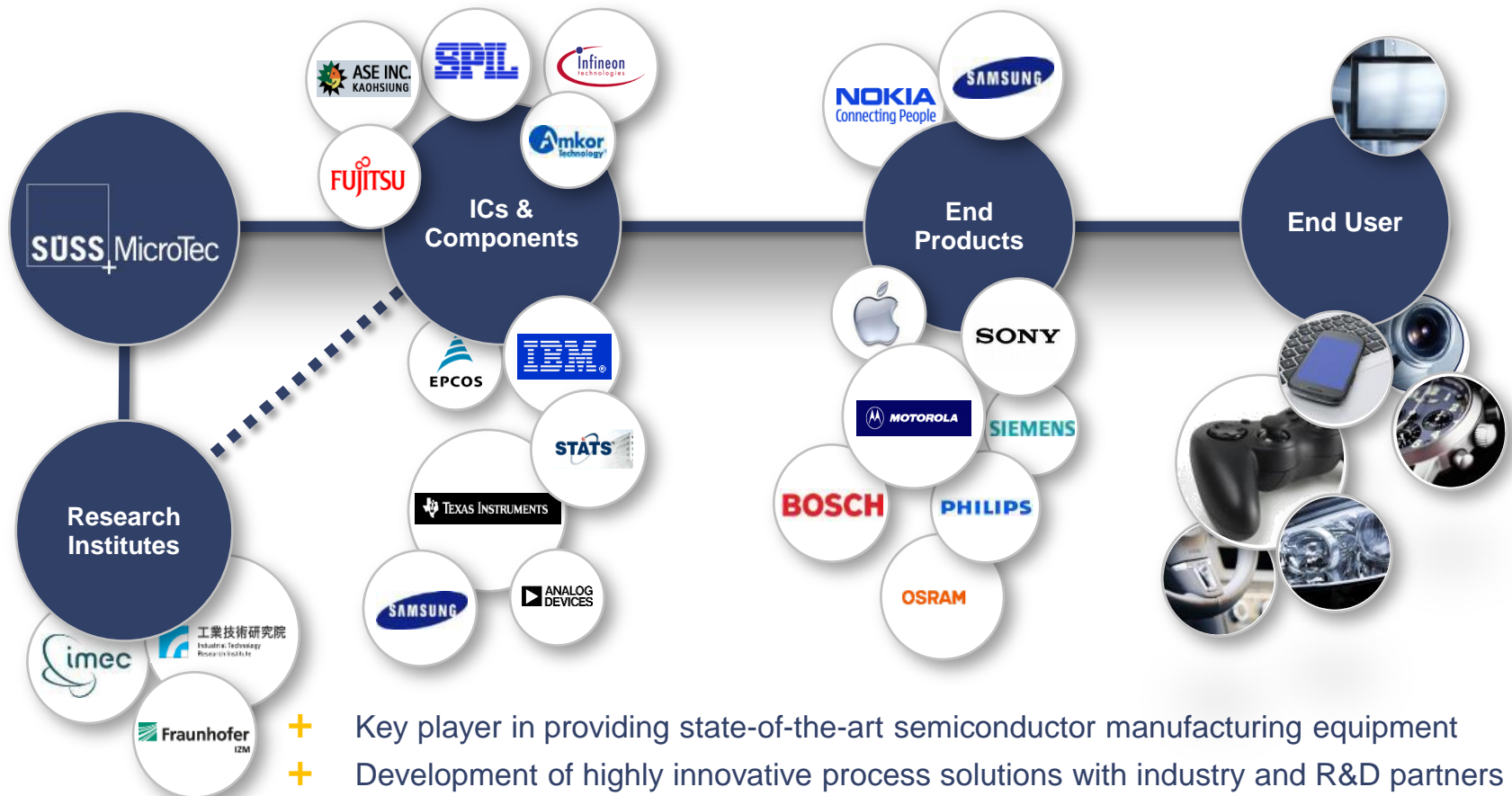
III. Growth Opportunities

IV. Financials

V. Outlook

- + A global leader in manufacturing equipment for the semiconductor mid- and backend market**
 - + Our equipment and process solutions create the micro structures that build and connect micro electronic devices**
 - + Focus on attractive growth markets: Semiconductors, MEMS and LED**
 - + Leading market position in target markets**
-
- + Key figures 2013:**
 - Order Entry € 135.0 million
 - Sales € 134.5 million
 - Employees: 655





- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative process solutions with industry and R&D partners
- + Key components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 18.9 € million
Sales 22.6 € million
Employees 120

EUROPE

Order Entry 41.9 € million
Sales 41.2 € million
Employees 410

ASIA

Order Entry 67.6 € million
Sales 65.5 € million
Employees 125



*Figures refer to the fiscal year 2013

MAIN PRODUCTION SITES

Germany

Sternenfels*

- + Development/production:
 - Bonder
 - Coater and Developer
 - Photomask Equipment
- + Core competencies:
 - Wet processing
 - Wafer bonding
 - Photomask Equipment
- + Production facility ~15,000 m²



Garching*

- + SUSS MicroTec HQ
- + Development/production:
 - Mask Aligner
 - Bond Aligner
- + Core competencies:
 - Exposure (proximity exposure)
 - Alignment
 - Bond Aligner
- + Production facility ~9,000 m²



USA

Corona (California)

- + Development/production:
 - Stepper/Scanner
 - Laser Processing
- + Core competencies:
 - Exposure (UV projection)
 - Laser Ablation



*Production site is owned by SUSS MicroTec

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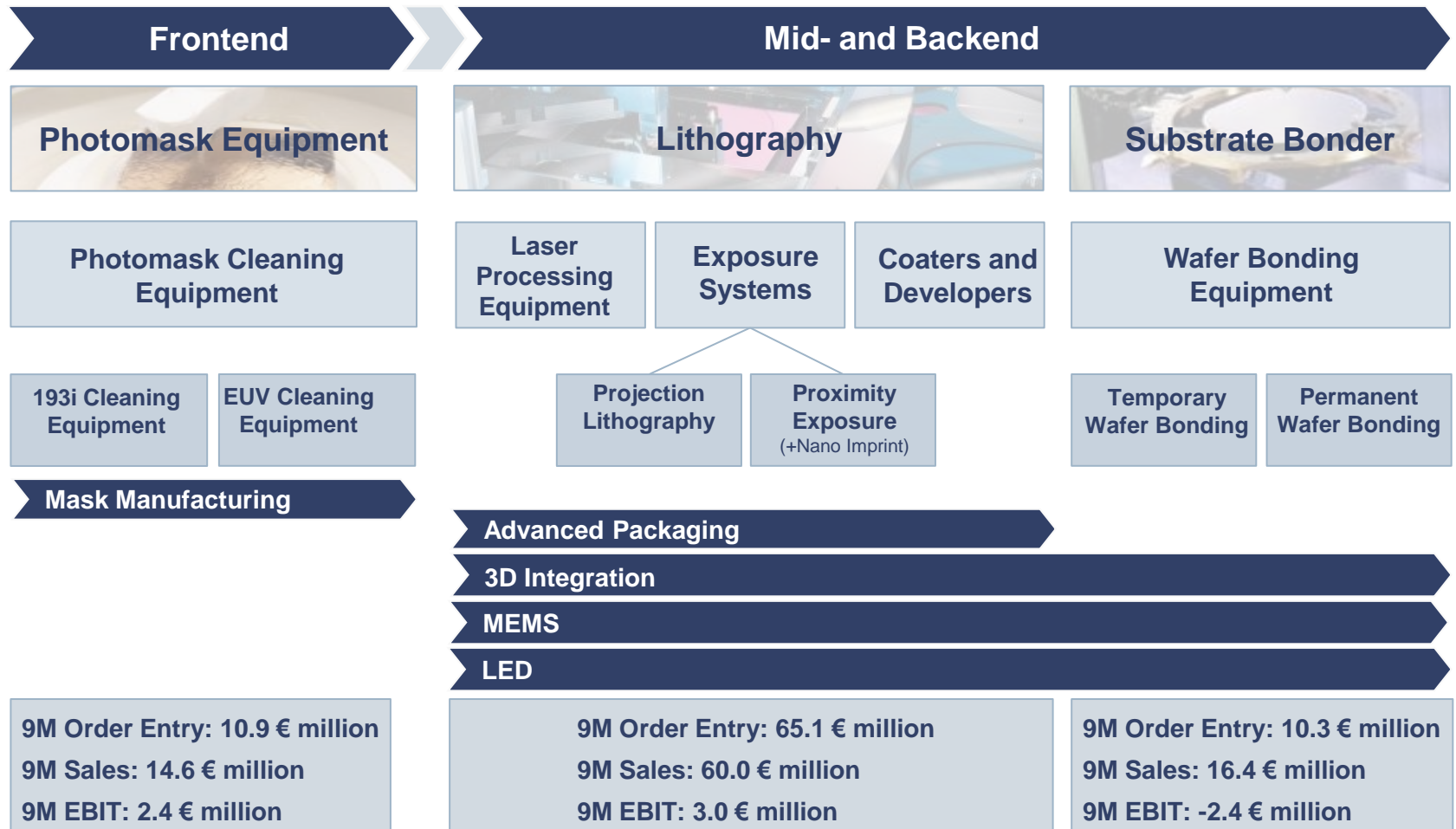
I. SUSS MicroTec at a Glance

II. **Products and Markets**

III. Growth Opportunities

IV. Financials

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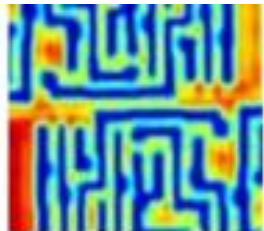


*9M EBIT Segment Others: -2.8 € million

Semiconductors

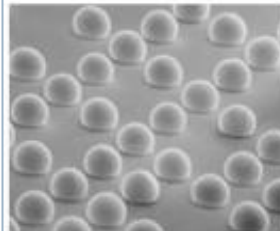
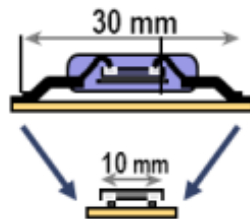
Mask Making

Photomask
Cleaning



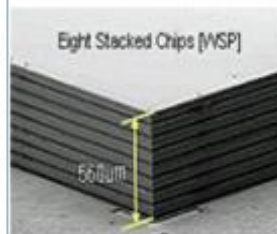
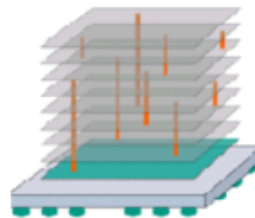
Advanced Packaging

Micro-Bumping



3D Integration

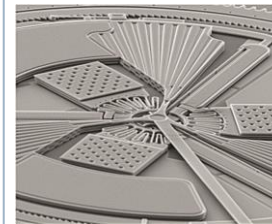
3D (TSV)
Stacking



Sensors

MEMS

Computing,
Automotive...



Lighting

LED

General Lighting,
HB and UHB

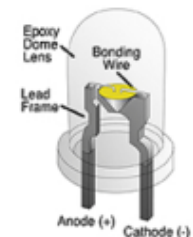


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Digital Lifestyle

- + The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- + Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- + New device generations offer higher functionality



E-Mobility

- + Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- + EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices and high performance ICs at the same time



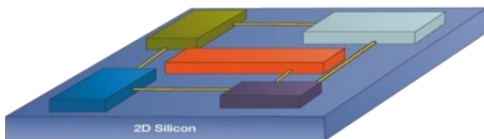
Energy Efficiency

- + Increased environmental awareness and rising energy cost drive the demand for energy efficient solutions i.e. solid state lighting
- + Energy efficiency in industrial production
- + Smart energy management in household applications



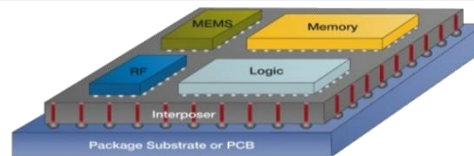
2D Packaging

- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size



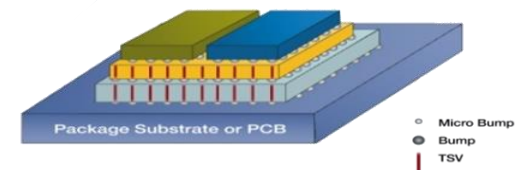
2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law



3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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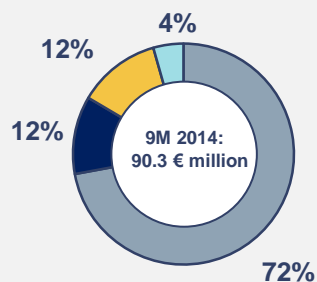
III. Growth Opportunities

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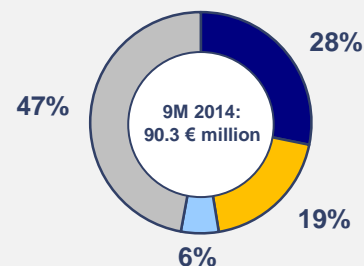
V. Outlook

ORDER ENTRY AND SALES BY SEGMENT AND REGION

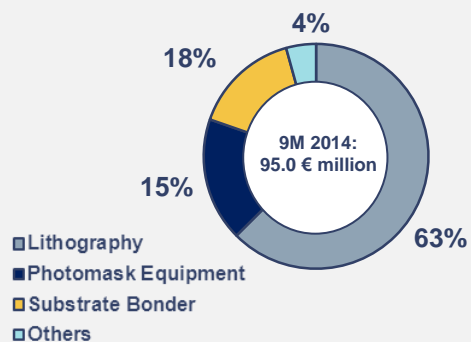
Order Entry by Segment



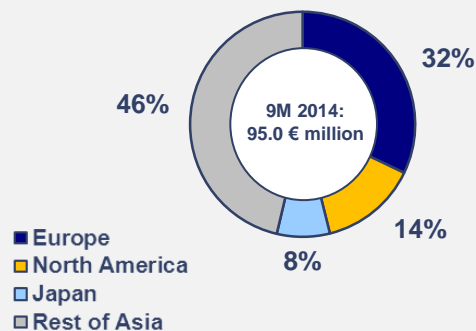
Order Entry by Region



Sales by Segment

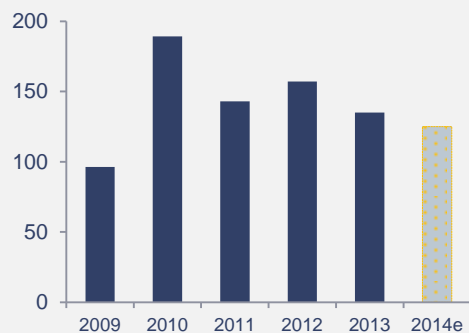


Sales by Region



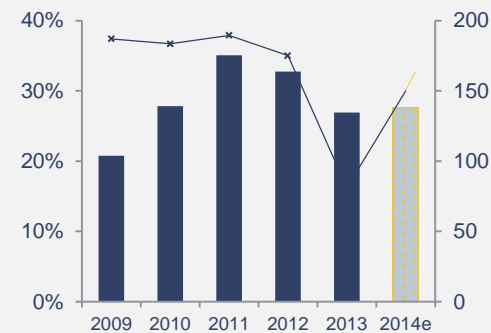
LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

Order Entry in € million

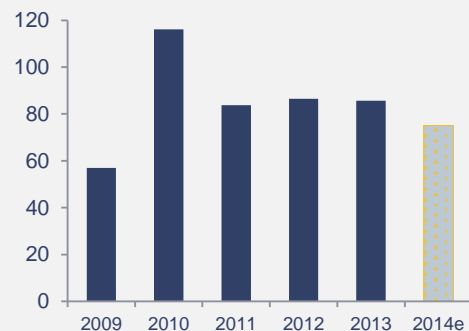


Sales and Gross Margin

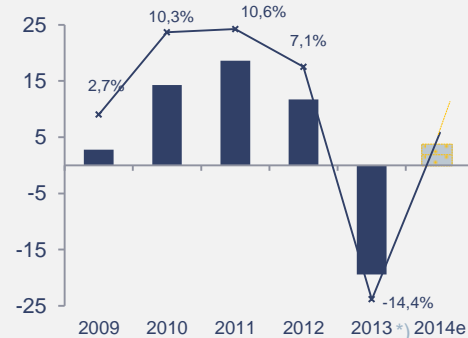
in € million



Order backlog in € million



EBIT in € million



* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding

KEY FINANCIALS

in € million	Q3 2014	Q3 2013	in %	9M 2014	9M 2013
Order Intake	29.1	34.3	-15.2%	90.3	105.9
Order Backlog 9/30	--	--	--	82.2	97.6
Revenue	25.6	38.9	-34.2%	95.0	94.0
EBIT	-3.3	1.8	--	0.1	-13.2
<i>EBIT in % of Sales</i>	-12.9%	4.6%	--	0.1%	-14.0%
Earnings after tax	-2.9	1.2	--	-0.9	-10.5
EPS in €	-0.16	0.06	--	-0.05	-0.55
Free Cash Flow*	-1.7	2.5	--	-4.1	-9.9
Net Cash	--	--	--	31.8	21.9
Employees 9/30	--	--	--	658	673

* before consideration of purchased interest-bearing securities

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Lithography	Mask Aligner and Coaters /Developers: Current and expected sales level around 80 – 90 € million per year UV Projection Scanners and Laser Ablation Steppers: Current annual sales at around 10 € million
Photomask Equipment	Stable sales level at around 20 € million per year
Substrate Bonders	Permanent Bonding and Temporary Bonding: Expected sales level of the division: 15 – 20 € million
Guidance	FY 2014: Sales: 135 to 145 € million EBIT: 2 to 4 € million Q4 2014: Order Intake: 30 - 40 € million

Business Environment/Targets

- + Enabling „Moore’s Law“ and „More than Moore“
- + Fundamental growth in target markets
- + Leveraging the existing technologies and core competencies into products
- + Grow revenue in the Lithography segment and bring the core business back to its former strength
- + Position SUSS MicroTec Photonic systems tools in the market and grow revenue
- + Generate a positive EBIT in the Substrate Bonder Division

Balance Sheet and P&L

- + (Maintain) tight cost structure
- + Strong financial position and positive free cash flow
- + Equity ratio > 60%
- + Target gross margins:
short-term 33 – 35%
medium-term >35%
- + Medium-term EBIT-margin of 5%+



Thank you!

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85748 Garching

www.SUSS.com

Management Board

Michael Knopp, CFO (Speaker)



Finance, Tax, Legal, HR, IT,
Sales, Service & Marketing,
Strategy, Investor Relations

Walter Braun, COO



Operations, Quality, Supply Chain
Management, R & D, Patents,
Environmental Protection, Work
Safety, Strategy

Divisions

Lithography

Photomask Equipment

Bonder

Sales & Service

Europe, USA, Japan, China, Taiwan, Singapore, Korea

Contact

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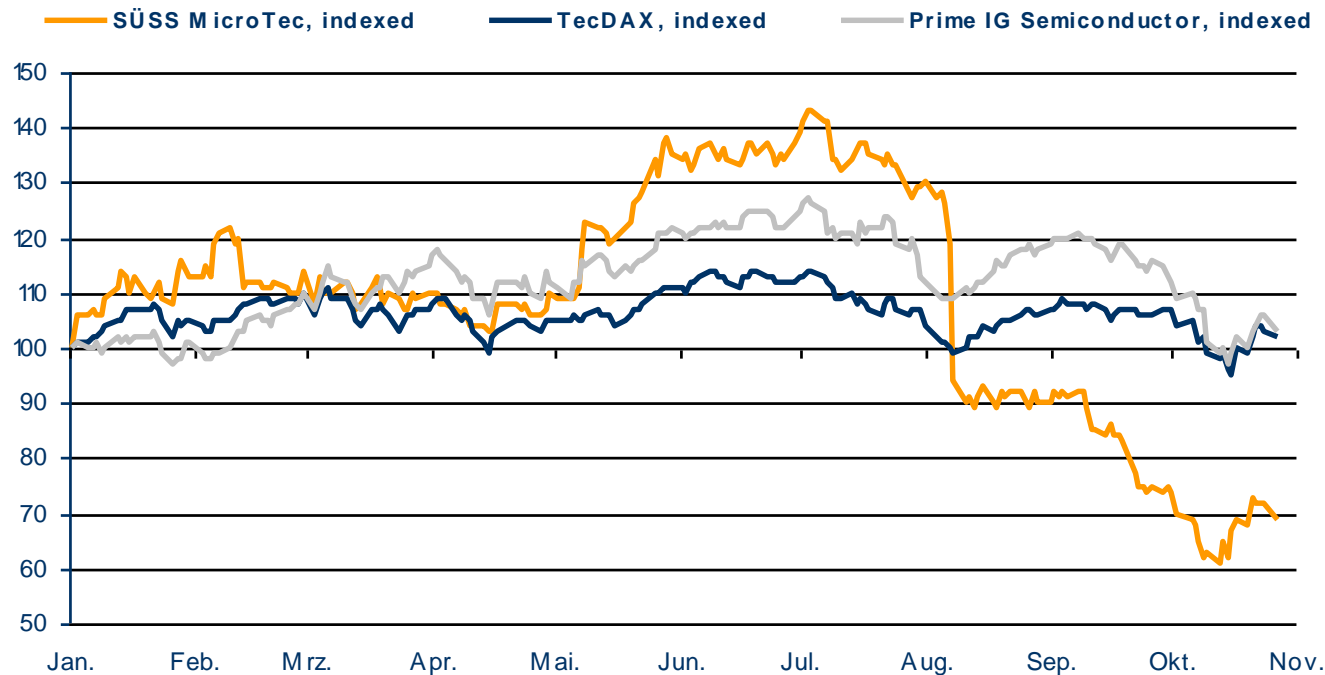
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Schleissheimer Strasse 90
85748 Garching (Munich)
Germany
www.suss.com

Financial Calendar 2015

KeplerCheuvreux Investment Conference, Frankfurt	19 Jan
Annual Report 2014	30 Mar
Quarterly Report 2015	8 May
Annual General Meeting 2015, Munich	2 Jun
Interim Report 2015	6 Aug
Nine-month Report 2015	5 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2014: 6.38 €)

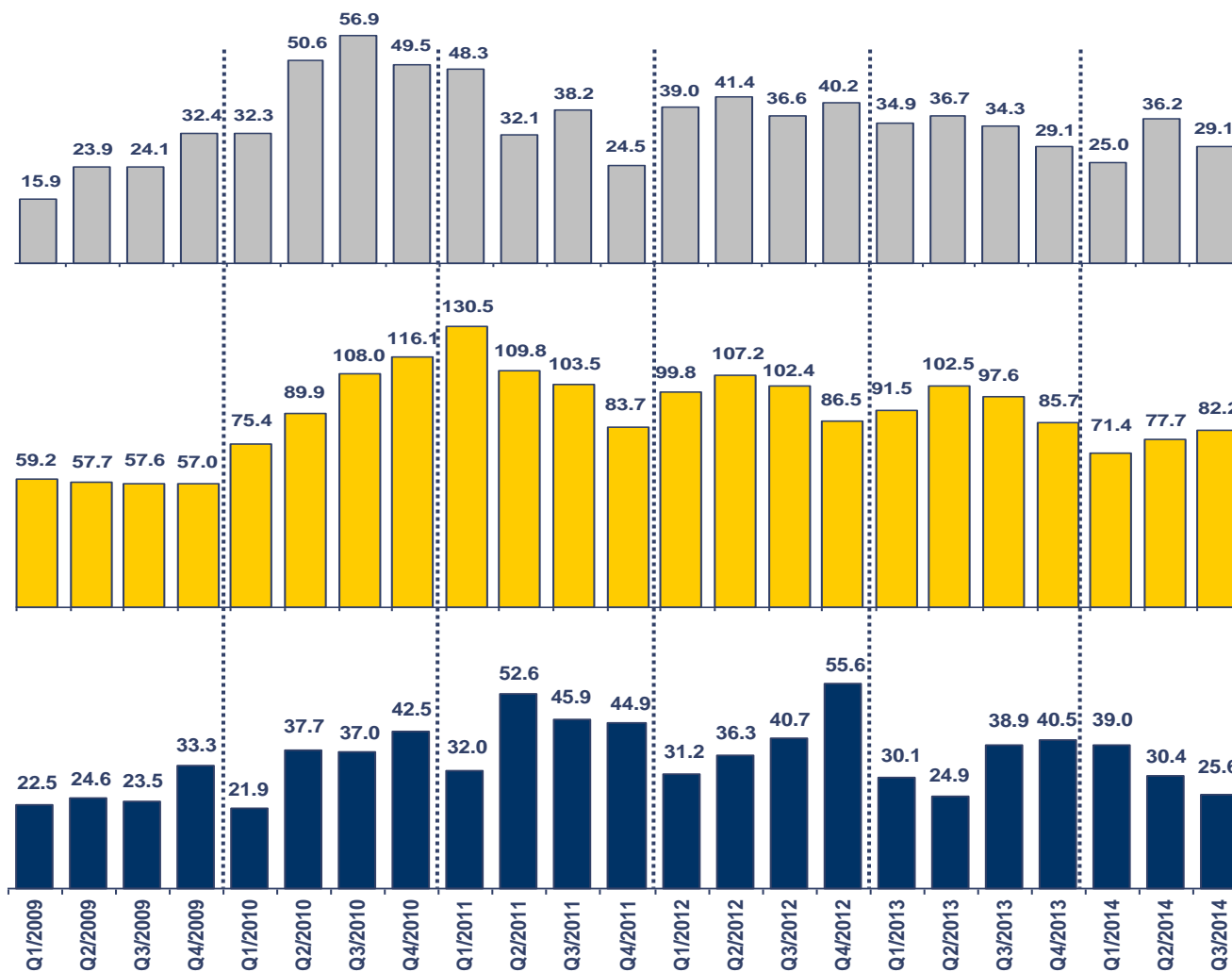


Major Shareholders:

Henderson	5.13%
ING Invest	3.42%
Vanguard	3.20%
Sycomore	3.14%
Schroders	3.10%
Baillie Gifford	3.00%

Average daily trading volume January 2014 – Oktober 2014: ~ 113,000

LONG TERM BUSINESS DEVELOPMENT BY QUARTER

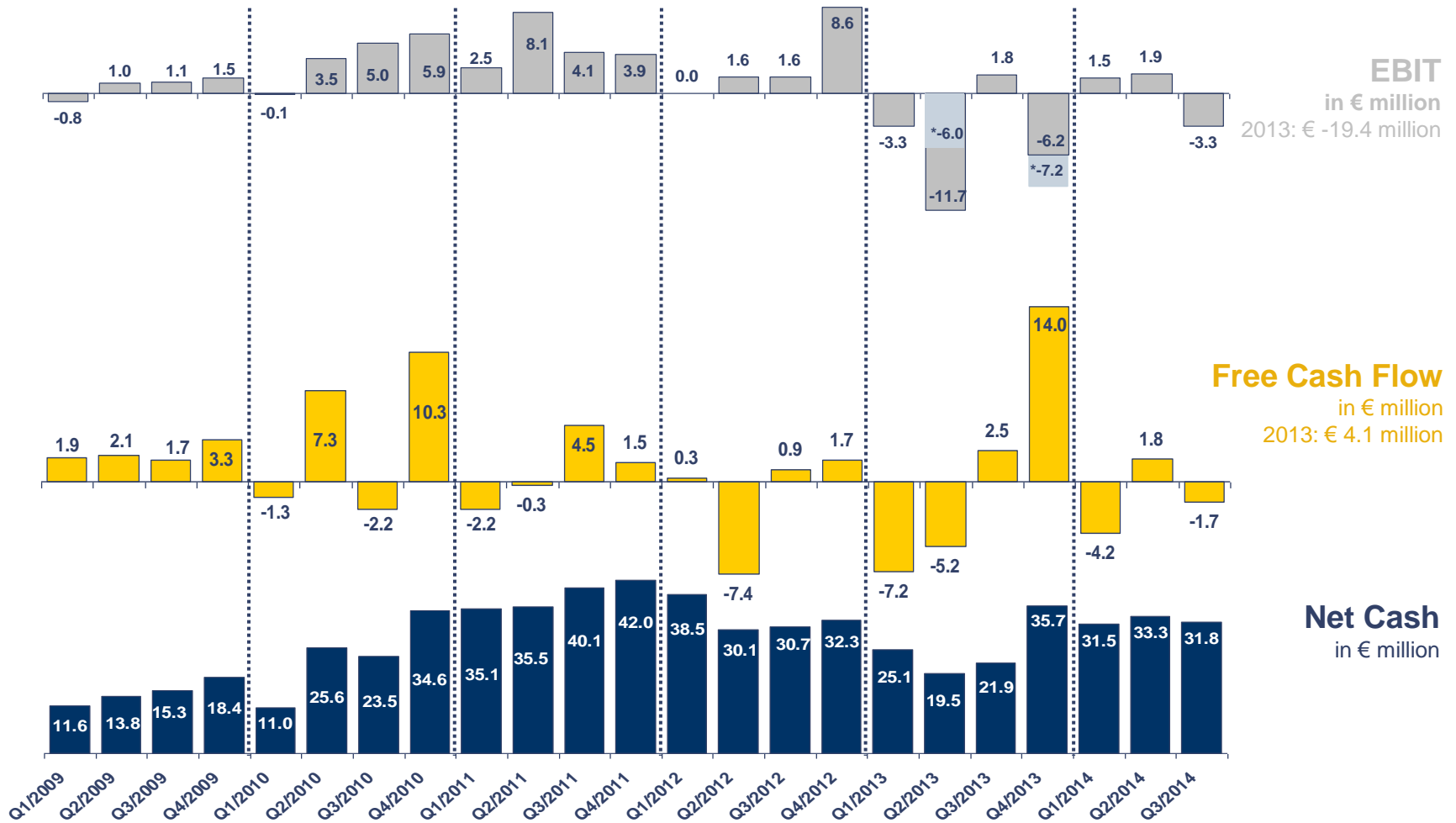


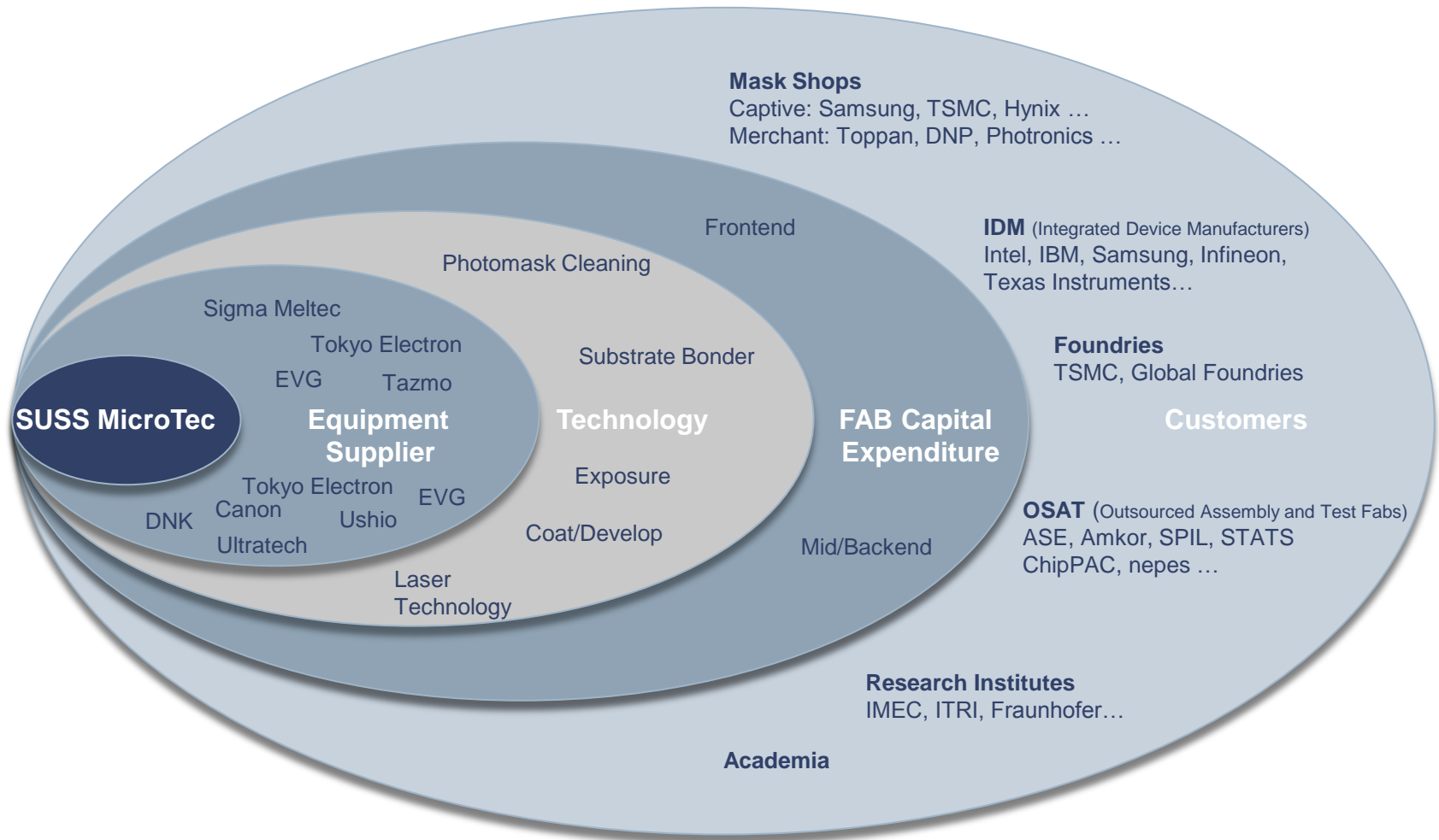
Order Entry
in € million
2013: € 135 million

Order Backlog
in € million

Sales
in € million
2013: € 135 million

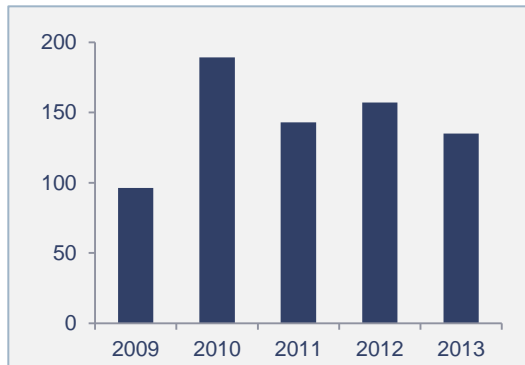
EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



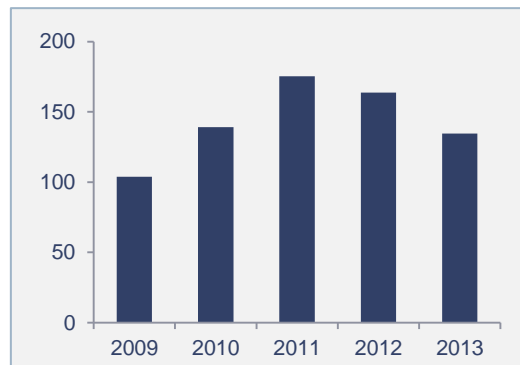


LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

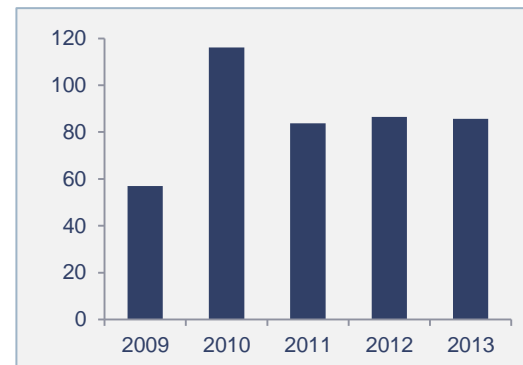
Order Entry in € million



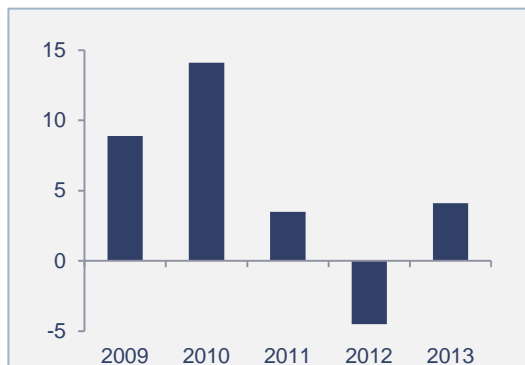
Sales in € million



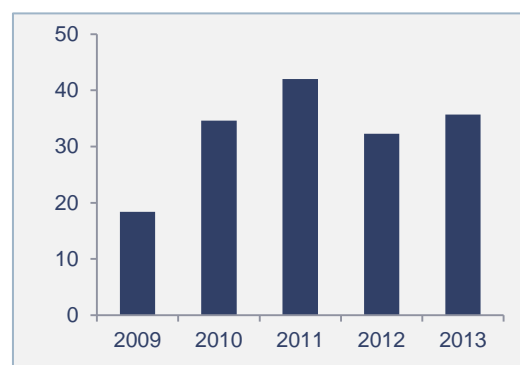
Order backlog in € million



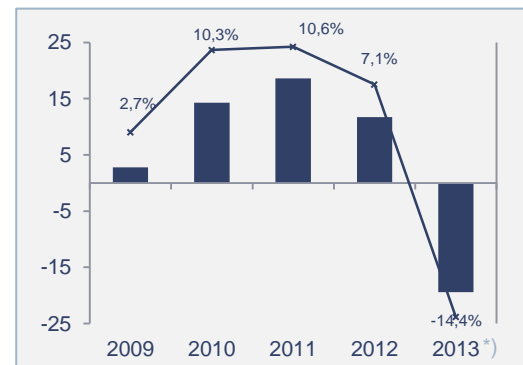
Free Cash Flow in € million



Net cash in € million



EBIT in € million



* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)